Direct Conversion
Empowered X-RAY Imaging

РЕНТГЕНОВСКИЕ СЕНСОРЫ И ДЕТЕКТОРЫ

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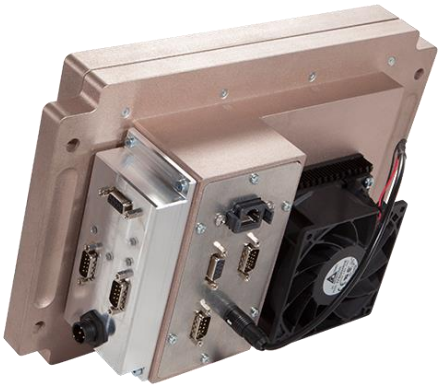
SNAP 100x2 - Industrial sensor (weld inspection, industrial CT, NDT)

SNAP100x2 is a flexible solution for soft X-ray (<20 kVp for 0.75 mm CdTe) to hard X-ray (320+ kVp with 1.4 mm CdTe) imaging.

The larger width of the imaging area produces high quality images even in low flux applications and the dual channel design allows uninterrupted data capture.

The compact enclosure of the sensor is well suited for integration in applications requiring portability, such as pipe weld inspection.

Despite the compact size, the device is temperature controlled for maximum performance.



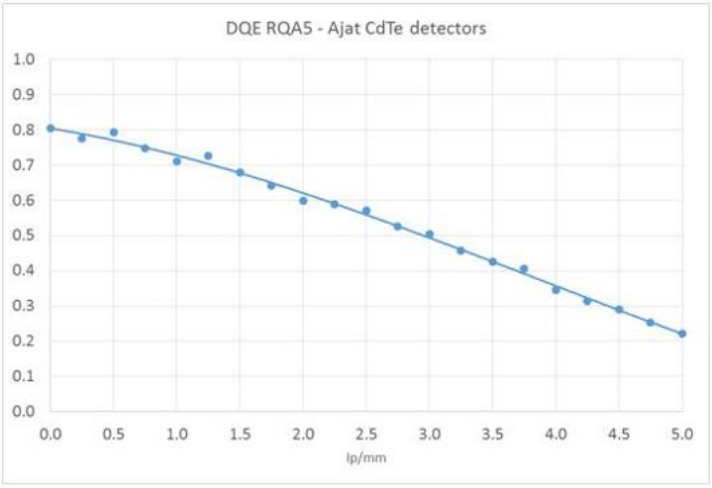
IMAGING PARAMETERS AND PERFORMANCE	
Pixel technology	Charge integration
Sensor thickness	0.75 mm or 1.4 mm CdTe
Pixel size	100 µm x 100 µm
Frame rate	10 to 300 fps
Configuration	2 columns of 4 hybrids each with 1.5 mm offset between columns
Active area size	width: 2 x 5.7 mm height: 98 mm
Pixel depth @ 300 fps	12-bit
MTF @ RQA5:	>70 % @ 2 lp/mm, >30 % @ 5 lp/mm
DQE @ RQA5:	>80% @ 0 lp/mm, >60 % @ 2 lp/mm, >20 % @ 5 lp/mm

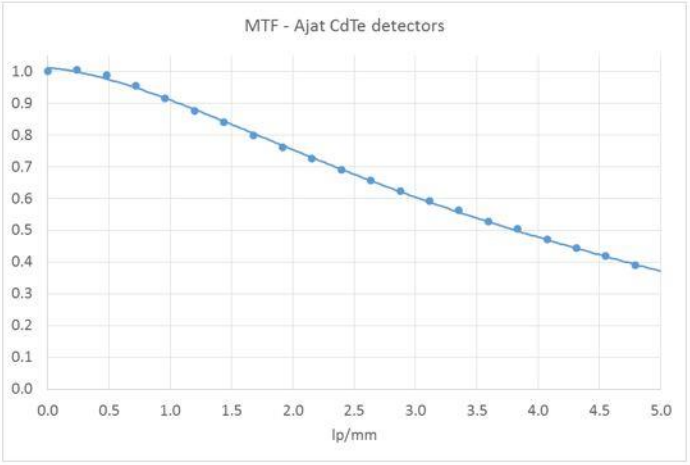
ENVIROMENTAL CONDITIONS	
Operating temperature range	+10 to +40 °C
Operating relative humidity	10 - 90 %
Storage temperature range	+5 to +45 °C
Transportation temperature range	-30 to +50 °C (max 2 days)
Tube kV range	15 kV to 300 kV
Temperature control	yes

ELECTRICAL INTERFACE	
Data interface	1000BASE-T Ethernet
Interface	Optoisolated I/O (5 V)
Power supply	24 V, ≤ 12 W without temperature control ≤ 60 W with temperature control

PHYSICAL DIMENSIONS	
Width x length x height	175 mm x 285 mm x 100 mm (excluding heat sink assembly)
Weight	3 kg (without TCU)

SOFTWARE	
Software included	Imaging application & Software Development Kit
Supported operating systems	Windows 7 – 10 Pro 32-bit or 64-bit





SNAP 150 - Dental sensor (panoramic, cephalometric)

SNAP150 is a compact X-ray sensor designed for dental panoramic X-ray imaging and other narrow beam X-ray applications
requiring the 150 mm active area.

Gigabit Ethernet interface combined with low power consumption and flexible, easy-to use software allow fast integration to any X-ray system.

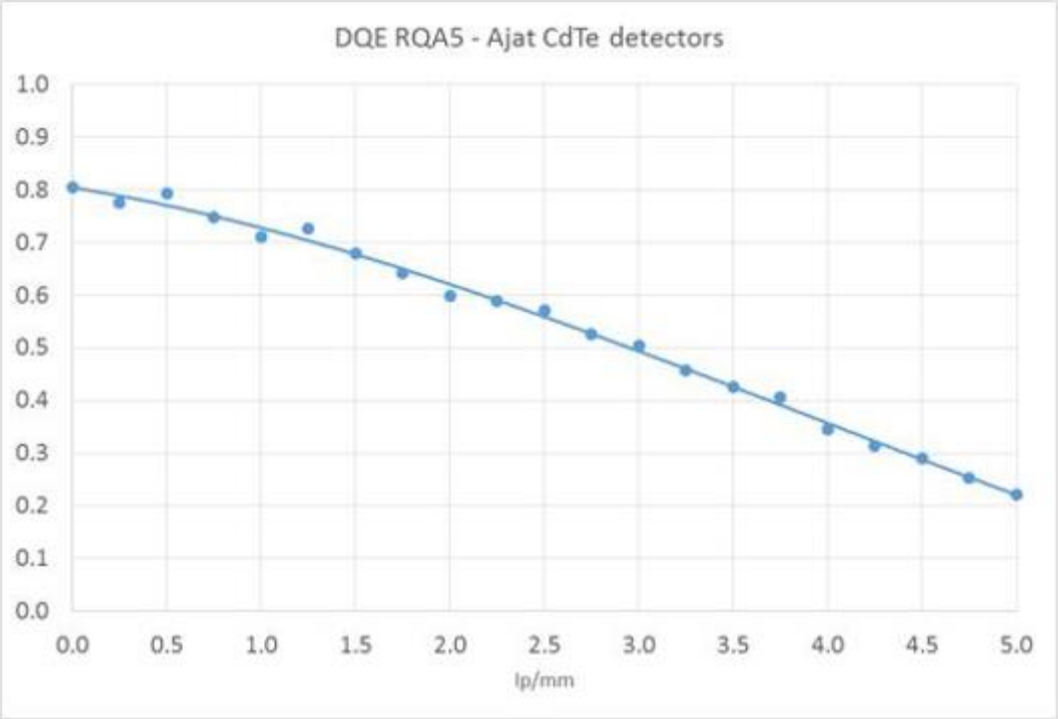
IMAGING PARAMETERS AND PERFORMANCE	
Pixel technology	Charge integration
Sensor thickness	0.75 mm CdTe
Pixel size	100 µm x 100 µm
Frame rate	up to 330 fps
Active area size	6.2 mm x 150.0 mm
Pixel depth	12-bit
MTF @ RQA5:	>70 % @ 2 lp/mm, >30 % @ 5 lp/mm
DQE @ RQA5:	>80% 0 lp/mm, >60 % @ 2 lp/mm, >20 % @ 5 lp/mm

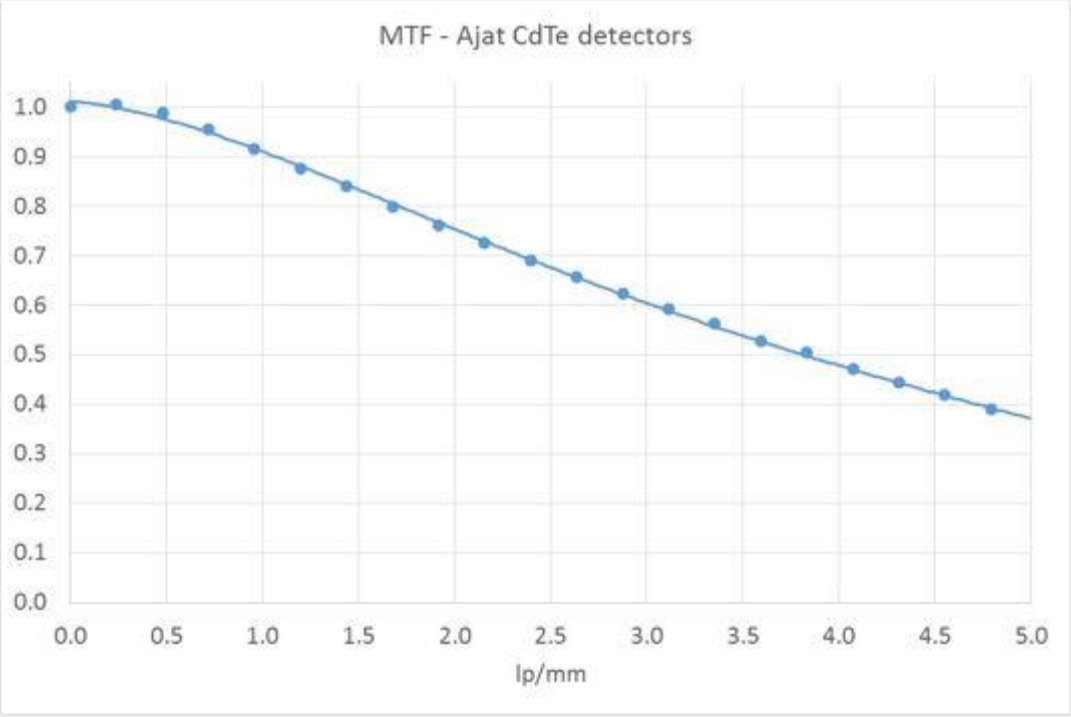
ENVIROMENTAL CONDITIONS	
Operating temperature range	+10 to +40 °C
Operating Relative Humidity	10 % - 95 %
Storage temperature range	+5 to +45 °C
Transportation temperature range	-30 to +50 °C

ELECTRICAL INTERFACE	
Data Interface	1000BASE-T Ethernet
Interface	Optoisolated I/O (+5V)
Power supply	12 V, 7 W

PHYSICAL DIMENSIONS	
Width x length x height	89 mm x 167mm x 5.4 mm
Weight	<1.5 kg

SOFTWARE	
Software included	Imaging application & Software Development Kit
Supported operating systems	Windows 7-10 32-bit and 64-bit





SNAP 225 - Dental sensor (panoramic, cephalometric)

The SNAP225 is a sensor well suited for dental X-ray imaging in both panoramic and cephalometric modalities in either fixed or movable sensor configurations. It can also be adapted to other X-ray imaging applications.

The unparalleled imaging performance produced by the CdTeCMOS technology is coupled with industry standard Gigabit Ethernet interface and flexible software solutions.

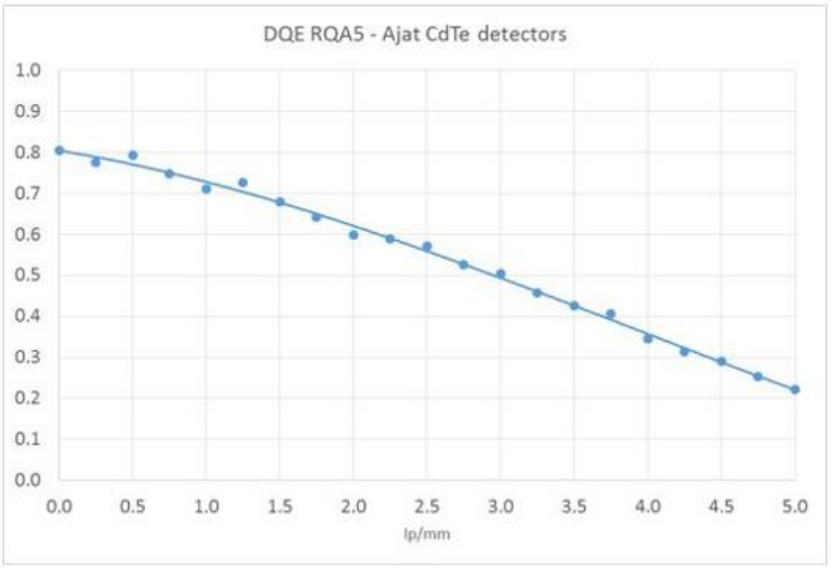
IMAGING PARAMETERS AND PERFORMANCE	
Pixel technology	Charge integration
Sensor thickness	0.75 mm CdTe
Pixel size	100 µm x 100 µm
Frame rate	300fps
Active area size	6.4 mm x 151.0 mm (panoramic modality) 6.4 mm x 226.6 mm (cephalometric modality)
Pixel depth @ 300 fps	12-bit
MTF @ RQA5:	>70 % @ 2 lp/mm, >30 % @ 5 lp/mm
DQE @ RQA5:	>80 % @ 0 lp/mm >60 % @ 2 lp/mm, >20 % @ 5 lp/mm
Scanning speed	≤30 mm/s at sensor plane

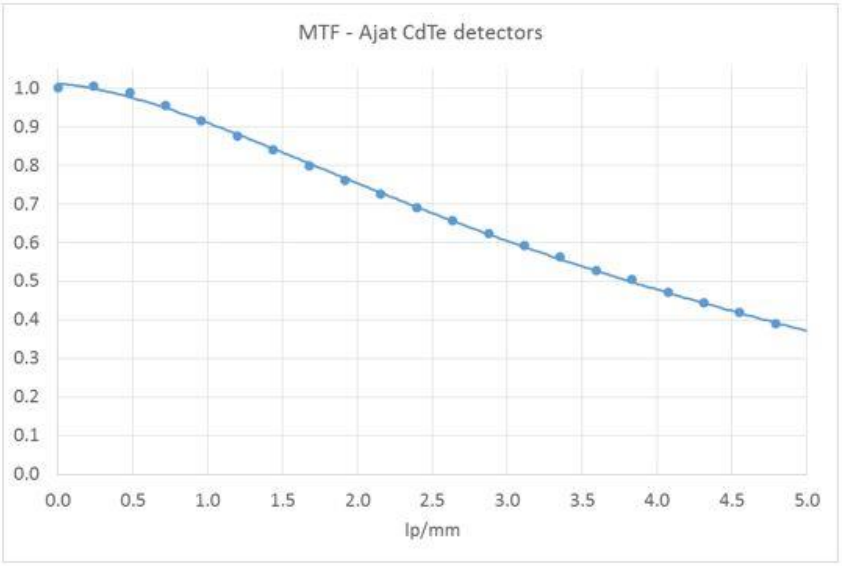
ENVIROMENTAL CONDITIONS	
Operating temperature range	+10 to +40 °C
Operating relative humidity	30 % - 75 %
Storage temperature range	+5 to +45 °C
Transportation temperature range	-30 to +50 °C (max 2 days)

ELECTRICAL INTERFACE	
Data Interface	1000BASE– T Ethernet
Interface	Optoisolated I/O (5V)
Power supply	24 V, 10 W

PHYSICAL DIMENSIONS	
Width x length x height	98 mm x 305 mm x 65.1 mm
Weight	3 kg

SOFTWARE	
Software included	Imaging application & Software Development Kit
Supported operating systems	Windows 7-10 32-bit and 64-bit



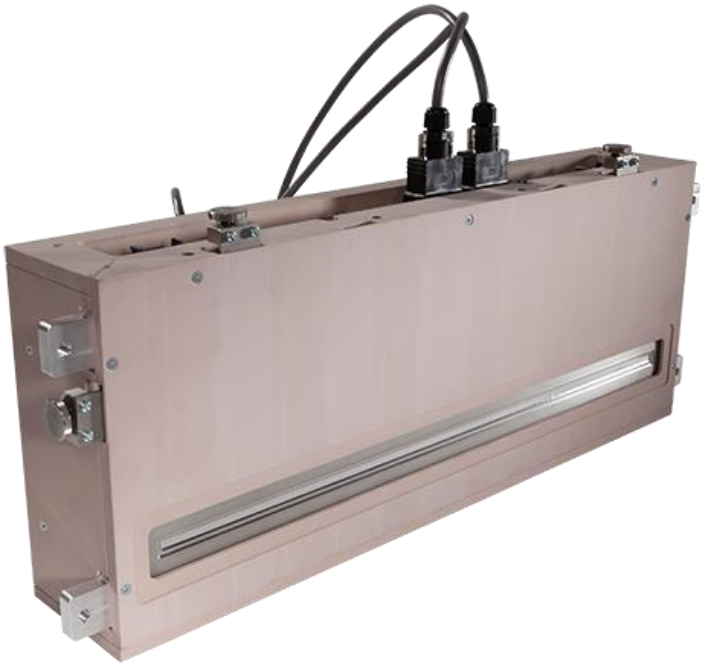


SNAP 450 - Industrial sensor (weld inspection, food inspection, NDT)

SNAP450 is an ideal solution for scanning and helical CT X-ray applications requiring larger imaging area.

The CdTe based sensor technology combined flexible imaging software provides incomparable image quality in an easy to integrate package.

Dual industry standard Gigabit Ethernet (1000Base-T) connections provide sufficient bandwidth to support the imaging speeds required.



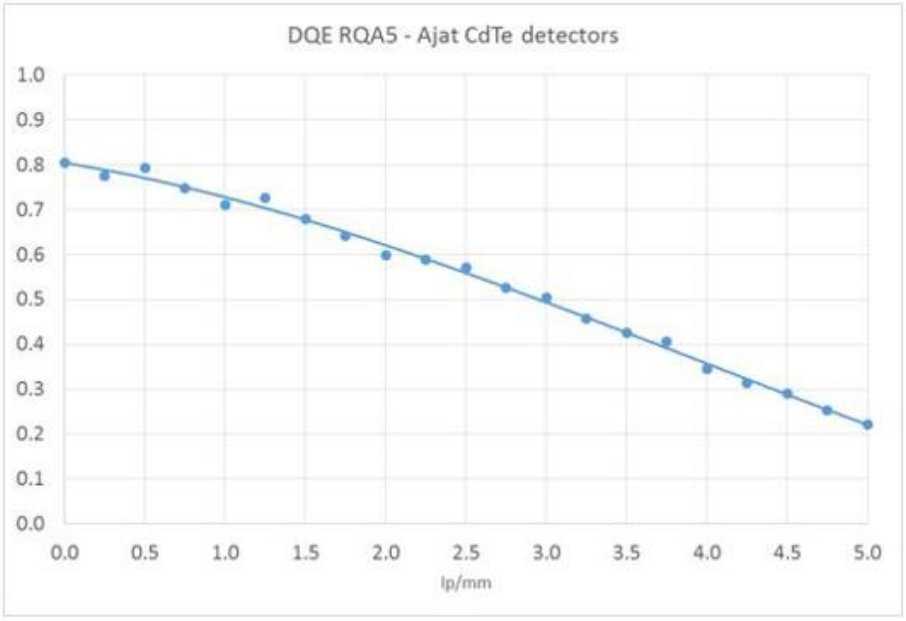
IMAGING PARAMETERS AND PERFORMANCE	
Pixel technology	Charge integration
Sensor thickness	0.75 mm CdTe
Pixel size	100 µm x 100 µm
Frame rate	300 fps
Active area size	6.4 mm x 453.0 mm
Pixel depth @ 300 fps	12-bit
MTF @ RQA5:	>70 % @ 2 lp/mm, >30 % @ 5 lp/mm
DQE @ RQA5:	>80% @ 0 lp/mm >60 % @ 2 lp/mm, >20 % @ 5 lp/mm

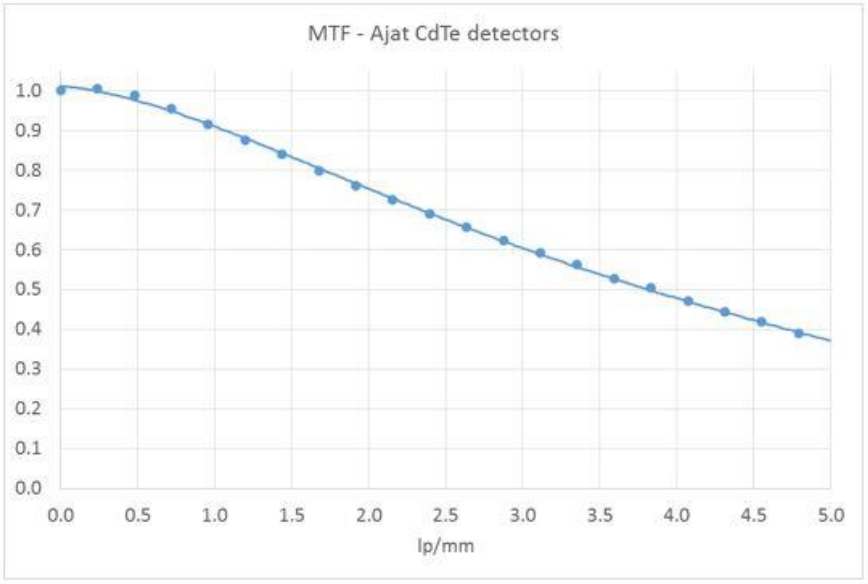
ENVIROMENTAL CONDITIONS	
Operating temperature range	+10 to +40 °C
Operating relative humidity	30 % - 75 %
Storage temperature range	+5 to +45 °C
Transportation temperature	-30 to +50 °C (max 2 days)
Temperature control	yes

ELECTRICAL INTERFACE	
Data interface	Dual link 1000BASE-T Ethernet
Interface	Optoisolated I/O (5V)
Power supply	24 V, ≤15 W

PHYSICAL DIMENSIONS	
Width x length x height	220 mm x 550 mm x 120 mm
Weight	10 kg (2 x TCU included)

SOFTWARE	
Software included	Imaging application & Software Development Kit
Supported operating systems	Windows 7-10 32-bit and 64-bit





ARISTO - Ultra high resolution sensor

ARISTO is a high resolution self triggering X-ray sensor designed for small field of view imaging. High resolving power is achieved with an ultra fine pitch directly converting silicon (Si) sensor. USB interface and self-triggering ensure ease of use and compatibility with any X-ray source in the range of 10 to 70 kVp.

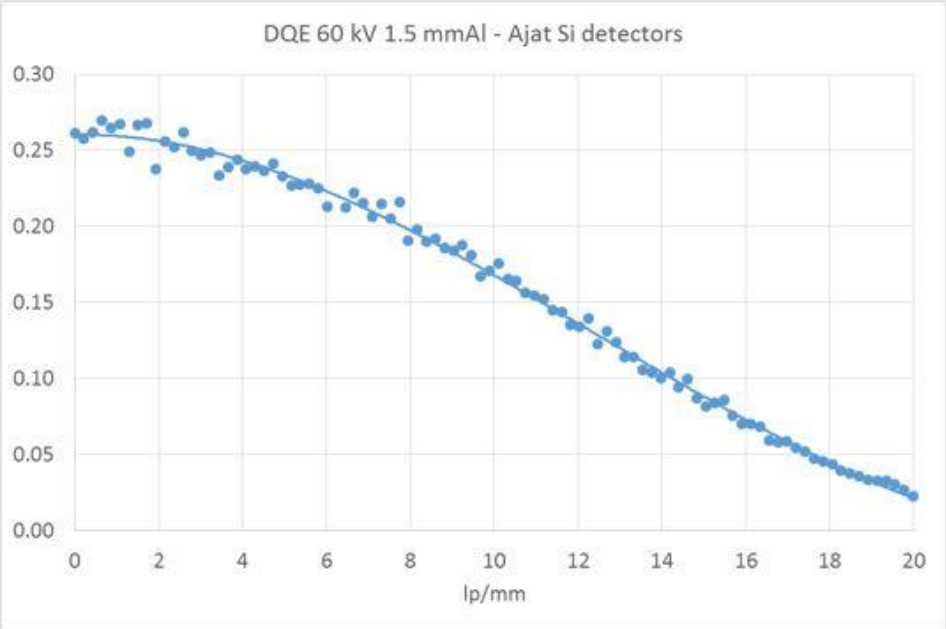
IMAGING PARAMETERS AND PERFORMANCE	
Pixel technology	Low power charge integration
Sensor thickness / material	0.5 mm, 1.0 mm, 1.3 mm / Si
Pixel size	25 µm x 25 µm
Image readout time	340 ms
Active sensor area	20 mm x 30 mm (800 x 1200 = 960k pixels)
Pixel depth	12-bit
MTF	80 % @ 5 lp/mm, 50 % @ 10 lp/mm, 10 % @ 20 lp/mm
DQE (1.0 mm Si) @ 60 kV 1.5 mmAl	25% @ 0 lp/mm, >20 % @ 5 lp/mm, >15 % @ 10 lp/mm

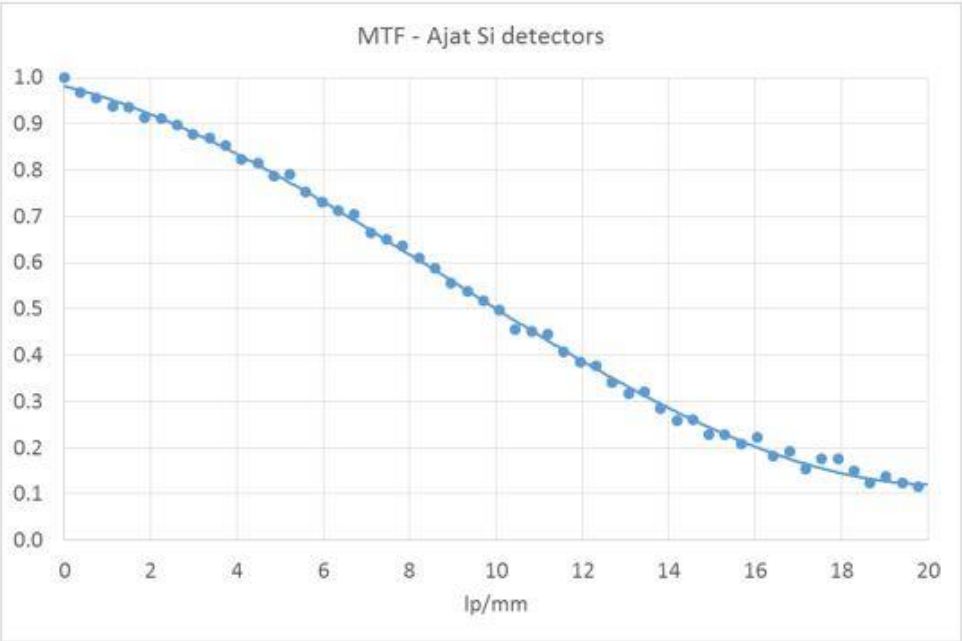
ENVIROMENTAL CONDITIONS	
Operating temperature range	+5 °C to +50 °C
Operating relative humidity	10 % to 95 %
Storage temperature range	+5 °C to +50 °C
Transportation temperature range	-30 °C to +50 °C (max 2 days)

ELECTRICAL INTERFACE	
Data interface	USB
Power supply	6 V, 1 W

PHYSICAL DIMENSIONS	
Width x length x height	117 mm x 164 mm x 34 mm

SOFTWARE	
Software included	Imaging application, Software Development Kit available on request
Supported operating systems	Windows 7 64-bit





DIC102H - Industrial sensor (tube-to-tubesheet weld inspection)

DIC102H is a highly specialized sensor designed for tube-to-tubesheet weld inspection in heat exchangers.

The unique layout of the detector area combined with a special X-ray source allows replacing films and isotopes with a faster, safer and more convenient digital solution.

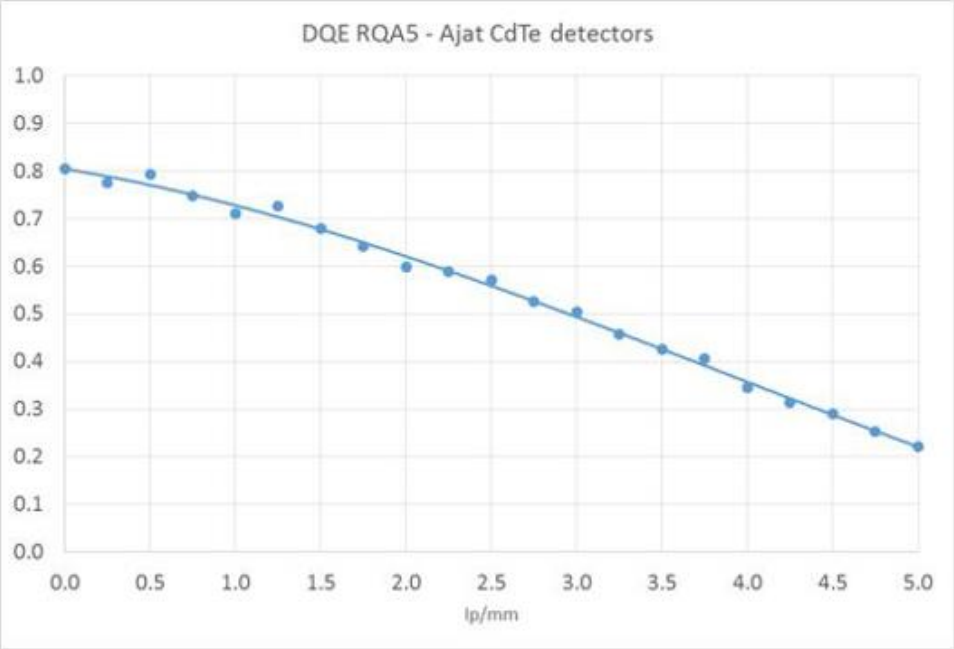
IMAGING PARAMETERS AND PERFORMANCE	
Pixel technology	Charge integration
Sensor thickness	0.75 mm CdTe
Pixel size	100 µm x 100 µm
Frame rate	10 - 150 fps
Active area size	8 hybrids of 127 x 253 pixels each
Pixel depth	12-bit
MTF @ RQA5:	>70 % @ 2 lp/mm, >30 % @ 5 lp/mm
DQE @ RQA5:	>80 % @ 0 lp/mm, >60 % @ 2 lp/mm, >20 % @ 5 lp/mm

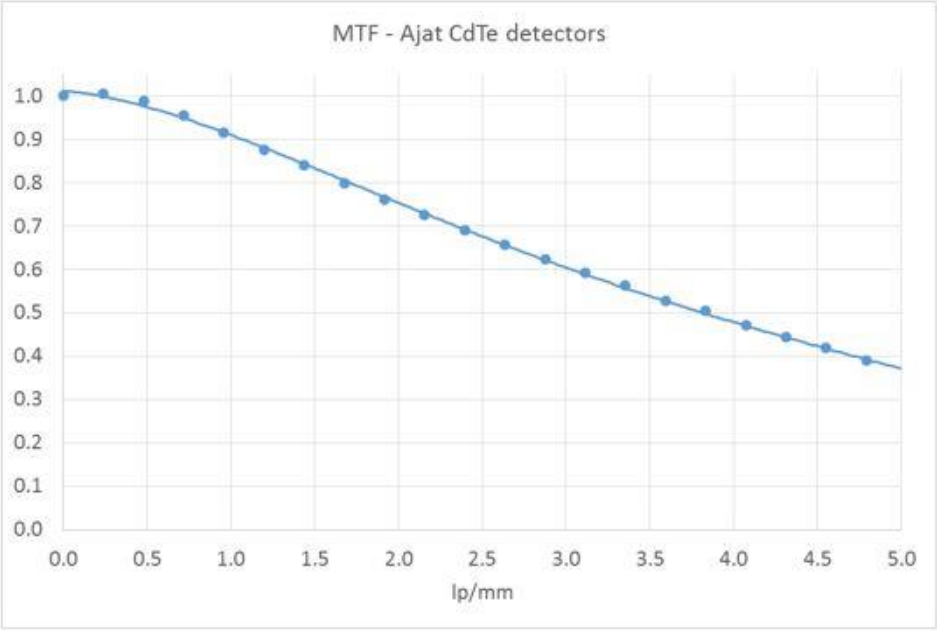
ENVIROMENTAL CONDITIONS	
Operating temperature range	+10 to +40 °C
Operating relative humidity	30 % - 75 %
Storage temperature range	+5 to +45 °C
Transportation temperature range	-30 to +50 °C (max. 2 days)

ELECTRICAL INTERFACE	
Data interface	1000BASE-T Ethernet
Power supply	Power over Ethernet 48V, 17W

PHYSICAL DIMENSIONS	
Width x length x height	160 mm x 164 mm x 67 mm
Weight	2 kg

SOFTWARE	
Software included	Imaging application & Software Development Kit
Supported operating systems	Windows 7-10 32-bit and 64-bit





SCAN300FL - Industrial sensor (weld inspection, industrial CT, NDT)

SCAN300FL is a high performance CdTe-CMOS sensor for narrow X-ray beam applications such as scanning or helical CT based products.

The temperature controlled enclosure provides maximum image equality even in varying environmental conditions while the CameraLink interface guarantees full data integrity even when the host PC is running CPU intensive processing.

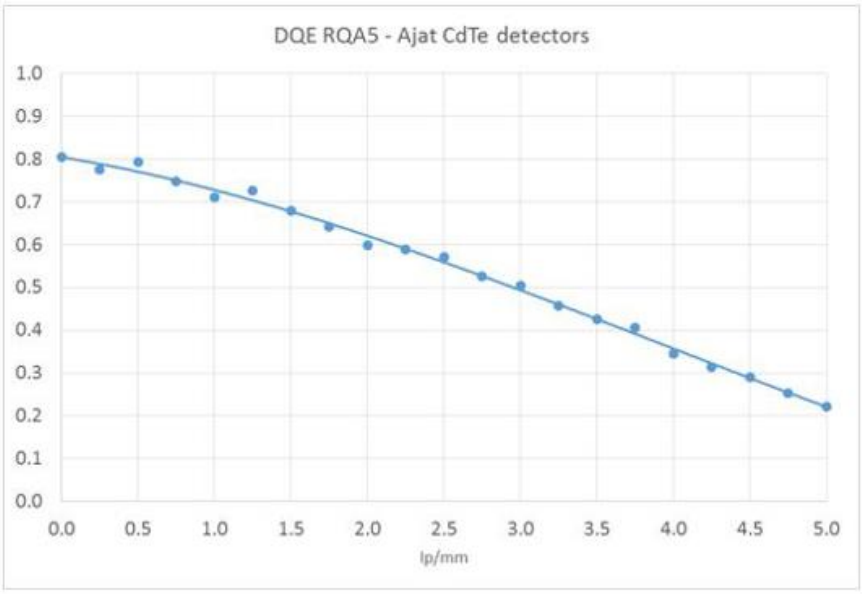
IMAGING PARAMETERS AND PERFORMANCE	
Pixel technology	Charge integration
Sensor thickness	0.75 mm CdTe
Pixel size	100 µm x 100 µm
Frame rate	up to 300.48 ± 0.021 fps
Active area size	6.0 mm x 220.0 mm
Pixel depth @ 300 fps	12-bit
MTF @ RQA5:	>70 % @ 2 lp/mm, >30 % @ 5 lp/mm
DQE @ RQA5:	>80 % @ 0 lp/mm, >60 % @ 2 lp/mm, >20 % @ 5 lp/mm DQE(0)

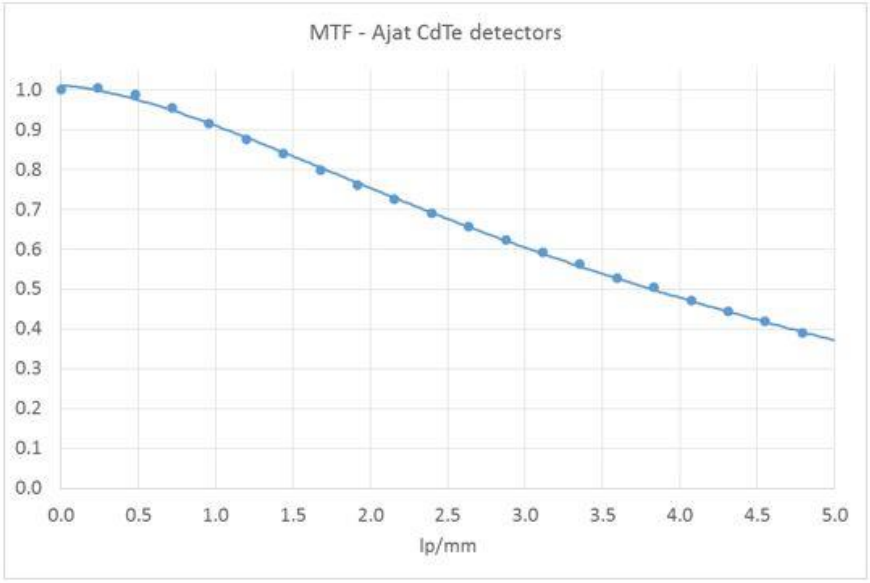
ENVIROMENTAL CONDITIONS	
Operating temperature range	20-30 °C (standard) 10-40 °C (extended)
Operating relative humidity	30 % - 80 %
Storage temperature range	+5 to +45 °C
Transportation temperature range	-30 to +50 °C
Tube kV range	10 kV to 200 kV
Temperature control	yes

ELECTRICAL INTERFACE	
CameraLink	Frame grabber
Interface	Optoisolated I/O (5V)
Power supply	AC/DC power supply (24V / 2.5A / 60W)

PHYSICAL DIMENSIONS	
Width x length x height	261 mm x 153 mm x 37 mm (excluding heat sink assembly)
Weight	2.4 kg

SOFTWARE	
Software included	Imaging application & Software Development Kit
Supported operating systems	Windows 7-10 32-bit and 64-bit





XC-Hydra series

The ultra-fast XC-Hydra detectors capable of 2m/s imaging at 100micron resolution bring new dimensions to medical applications and a broad range of NDT applications.

Technology

The XC-Hydra series is the fastest direct-digital, dual-energy, photon-counting X-ray detector on the market. Developed around the Direct Conversion group's powerful CdTe-CMOS hybrid sensor, the Hydra brings new capabilities to fast line-scanning applications. The Hydra sensor provides outstanding imaging in either frame or Time-Delayed Summation (TDS) mode, with a scan speed potential of an incredible 2 m/s without the need for pixel binning.

XC-Hydra detectors come in three active area lengths: 20 cm, 35 cm and 50 cm. Being a detector that is ideal for fast scanning solutions it has a sensor width of 0.6 cm across the range, and comes with two options of CdTe thicknesses: 0.75 mm for standard energy applications and 2 mm for high energy X-ray applications.

Dual-energy acquisition with anti-coincidence technology is a key factor in the advanced capabilities of all XC-Hydra detectors. During dual-energy acquisition, the energy of the detected photon is compared to two independent thresholds which are read out separately. The two energy sets can be used for material differentiation, opening the door to new imaging techniques in both medical and industrial X-ray. Most critically the XC-Hydra series detectors have the fastest commercially available anti-coincidence technology, which produces superior energy resolution by ensuring the attribution of each single photon signal to the correct pixel. This powerful anti-coincidence (charge sharing) technology operates across the full length of the detector at ultra-fast speeds.

Application

The ultra fast imaging capability of XC-Hydra detectors mean that images can be acquired with no compromise of the 100 micron pixel size. This speed, when coupled with the dual energy capability, and the market leading MTF and DQE make the XC-Hydra detector range ideal for in-line inspection applications such as food inspection, PCB inspection and DUPRO.

With its market leading sensitivity, the Hydra captures high quality images at very low radiation exposure making it perfect for medical applications such as full body and extremity scanning and other radiological investigative work.

Integration

The Hydra sensor is connected to the computer via a GigE interface. The detector comes with a fully flexible software development kit which runs on Windows 7 upwards. The detector is bundled with engineering software which exposes the various functionalities available.

- Dual energy for material differentiation
- Unsurpassed levels of MTF and DQE
- Ultra-fast X-ray imaging >2m/s

Technical Specification

Physical

Dimensions l x w x h	
XC-Hydra FX20	276mm x 120mm x 66mm
XC-Hydra FX35	428mm x 120mm x 66mm
XC-Hydra FX50	585mm x 120mm x 66mm
Temperature Control	Internal Peltier Temperature Control + PWM Controlled Fan System
Operating Temperature Range	+15 to +35 °C @ 30% – 85% humidity (non-condensing)
Tile gap	100µm
X-ray window	Carbon fiber, 1.5mm thick
X-ray shielding	Depending on application

Sensor

Sensor type	Dual-Energy Photon Counting CdTe-CMOS
Sensor thickness options	0.75mm : Standard energy applications 2mm : High energy applications
Active area	
XC-Hydra FX20	206mm x 6mm
XC-Hydra FX35	350mm x 6mm
XC-Hydra FX50	510mm x 6mm
Tile gap	100µm
Pixel size	100µm
Pixel fill factor	100%

Perfomance

Imaging speed (Frame mode)	
XC-Hydra FX20	300fps
XC-Hydra FX35	200fps
XC-Hydra FX50	150fps
Imaging speed (TDS mode)	
XC-Hydra FX20	Up to 10,000 lines/s
XC-Hydra FX35	Up to 10,000 lines/s
XC-Hydra FX50	Up to 5,000 lines/s
Counter output range	16 bits (Frame mode) ; 32 bits (TDS mode)

Detective Quantum Efficiency : DQE (0) typical	RQA5 spectra, 6μGy, SID 1m 0.75mm CdTe 80% 2.0mm CdTe 80%
Modulation Transfer Function : MTF	80% @ 2lp/mm 45% @ 5lp/mm
Lag	0% (after X-ray 6μGy)
Ghosting	0.1% 1 min after x-rays (6 μGy)
Tube kV range	up to 160kVp normal up to 300kVp with added shielding
External Trigger Available	Opto-coupled 5V, 12-24V with external resistor

XC-Thor Series

The robust dual-energy XC-Thor series with its IP67 housing, brings high performance, fast imaging to the industrial sector.

Technology

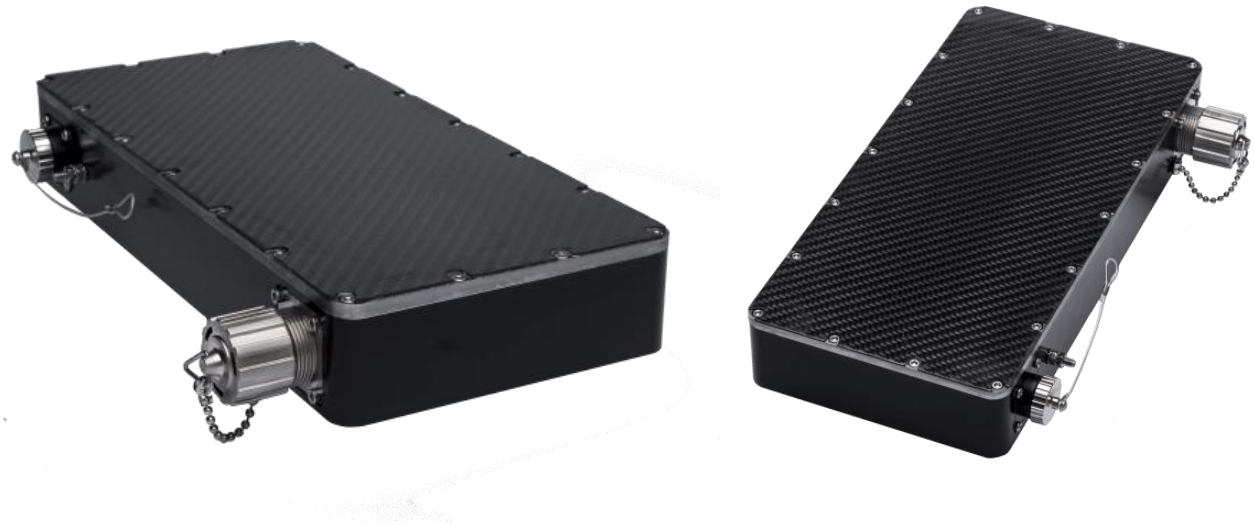
XC-Thor detectors are dual energy, photon-counting, direct conversion, X-ray sensors in a robust IP67 rated housing. Employing the very high efficiency direct conversion CdTe-CMOS technology at their core, XC-Thor detectors provide outstanding digital image quality for challenging environmental conditions. With the ability to be operated in Frame mode or Time Delayed Summation (TDS) mode this versatile detector can provide solutions for both scanning and single imaging requirements.

The XC-Thor range has the additional benefit of dual energy acquisition with anti-coincidence technology. During dual energy acquisition the energy of the detected photon is compared to two independent thresholds which are read out separately. The two energy sets can be used for material separation, opening the door to new imaging techniques in both medical and industrial X-ray. Anti-coincidence technology allows superior MTF through attributing each single photon signal to the correct pixel.

Application

With a combination of standard sensor active areas ranging in length from 10 cm to 15 cm; widths of 1.25 cm and 2.5 cm (larger sizes available on request); and 0.75 mm CdTe standard energy and 2 mm CdTe high energy versions, XC-Thor detectors are used in a broad range of applications.

Its robust build makes its particularly useful in weld integrity testing where the detector can be dropped into an existing mechanical scanning system, and field inspection applications where portability is important.



Integration

XC-Thor detectors are connected to the computer via a GigE interface. The detector comes with a fully flexible software development kit which runs on Windows XP, Vista and Windows 7. The detector is bundled with engineering software which exposes the various functionalities available

- Up to 300 kV, more with ultra-high kV options
- Unsurpassed levels of MTF and DQE
- 1000 fps at 100micron resolution

Technical Specification

Physical	
Dimension l x w x h (without optional cooling system)	178mm x 140mm x 46mm
Temperature Control	Internal Peltier temperature control
X-ray window	Carbon fiber, 1.5 mm thick
X-ray shielding	Depending on application

Sensor	
Sensor type	Dual-Energy Photon Counting CdTe-CMOS
Sensor thickness options	0.75mm : Standard energy applications 2mm : High energy applications
Active area XC-Thor FX8 XC-Thor FX10	80mm x 12.8mm 80mm x 25.6mm 100mm x 12.8mm 100mm x 25.6mm
Tile gap	100µm
Pixel size	100µm
Pixel fill factor	100%

Perfomance	
Imaging speed (Frame mode)	up to 300fps (1000fps burst mode)
Imaging speed (TDS mode)	up to 10000lps
Internal counter range	12 bits (Frame mode) 18 bits (TDS mode)
Counter output range (TDS mode)	16 bits Frame mode, 32 bits TDS mode
Detective Quantum Efficiency : DQE (0) typical	RQA5 spectra, 6µGy, SID 1m 0.75mm CdTe 75% 2.0mm CdTe 75%
Modulation Transfer Function : MTF	75% @ 2lp/mm 40% @ 5lp/mm
Lag	0% (after X-ray6uGy)
Ghosting	<0.1% 1 min after x-rays (6uGy)
Tube kV range	up to 300kVp (ultra high kV versions available on request)
External trigger available	Opto-coupled 5V, 12-24V with external resistor

XC-Actaeon series

The XC-Actaeon product line brings the high speed, photon counting direct conversion technology to small area detector applications. Powered by Direct Conversions powerful CdTe-CMOS hybrid sensor at its core, the XC-Actaeon delivers market leading levels of MTF and DQE across a broad range of X-ray applications.

Technology

The XC-Actaeon product line brings the high speed photon counting direct conversion technology to small area detector applications. Powered by Direct Conversions powerful CdTe-CMOS hybrid sensor at its core, the XC-Actaeon delivers market leading levels of MTF and DQE across a broad range of x-ray applications.

With four sizes of standard active area XC-Actaeon detectors can be used in standard energy applications when configured with 0.75 mm or 2 mm thick CdTe for high energy X-ray imaging.

Dual-energy acquisition with anti-coincidence technology is a key factor in the advanced capabilities of the XC-Actaeon. During dual-energy acquisition, the energy of the detected photon is compared to two independent thresholds that are read out separately. The two energy sets can be used for material differentiation, opening the door to new imaging techniques in both medical and industrial X-ray. As with other products in the XCounter range the XC-Actaeon detectors have the fastest commercially available anti- coincidence technology, which produces superior energy resolution by ensuring the attribution of each single photon signal to the correct pixel.

Application

XC-Actaeon detectors bring advantages to a wide range of applications ranging from Micro-CT to industrial process line inspection. The Actaeon also aid dual energy material decomposition investigation, particularly in small sample analysis, PCB investigation, and foreign object inspection.

High speed, high flux applications or single frame imaging at high sensitivity, can all be supported by the versatile XC-Actaeon which delivers market leading MTF and DQE across all requirements.

Integration

The XC-Actaeon is connected to the computer via a GigE interface. The detector comes with a fully flexible software development kit which runs on Windows 7 upwards. The detector is bundled with engineering software which exposes the various functionalities available.

- Unsurpassed levels of MTF and DQE
- Up to 2500fps imaging at 100 micron
- Dual energy for material differentiation

Technical Specification

Physical

Dimension l x w x h All sensor area types	276mm x 120mm x 66mm
Operating temperature range	+15 – +35 °C @ 30% – 85% humidity (non-condensing)
X-ray window	Carbon fiber, 1.4 mm thick
X-ray shielding	Depending on application

Sensor

Sensor type	Dual-Energy Photon Counting CdTe-CMOS
Sensor thickness options	0.75mm : Standard energy applications 2mm : High energy applications
Active area	
XC-Actaeon FX1	13mm x 26mm
XC-Actaeon FX2	26mm x 26mm
XC-Actaeon FX3	39mm x 26mm
XC-Actaeon FX5	52mm x 26mm
Tile gap	100µm
Pixel size	100µm

Performance

Imaging speed (Frame mode)	
XC-Actaeon FX1	800fps
XC-Actaeon FX2	400fps
XC-Actaeon FX3	250fps
XC-Actaeon FX5	200fps
Frame summing mode	10kHz fps
Binning	2×2, 4×4, 8×8
Sensor mode	Output summed to one pixel
Counter output range	16 bits (Frame mode) ; 32 bits (TDS mode)
Acquisition time	200ns to 1 s
Detective Quantum Efficiency DQE (0) typical	RQA5 spectra, 6µGy, SID 1m 0.75mm CdTe >80% 2.0mm CdTe >80%
Modulation Transfer Function	80% @ 2lp/mm
MTF	45% @ 5lp/mm
Lag	0% (after X-ray 6µGy)
Ghosting	0.1% 1 min after x-rays (6 µGy)
External trigger available	Opto-coupled 5V, 12-24V with external resistor

Direct Conversion
Empowered X-RAY Imaging

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